PRODUCT DATA SHEET

Purolite™ CriticalResin™ NRW1100

聚苯乙烯 凝胶, 强酸阳离子树脂, 氢型, 均颗粒, 核级

主要应用

- 去污 - 锂一回路
- 混床 阳离子组分
- 额外层-增加的阳离子交换容量

适用系统

- 阳树脂罐

包装样式

- 1CF 纸盒
- 5 CF 纤维板桶

典型物理和化学参数

聚合物骨架	凝胶型聚苯乙烯二乙烯苯交联
外观	球状颗粒
官能团	磺酸
离子型态	H+ 型
全交换容量（最小）	2 eq/L (43.7 Kgr/ft³) (H+ 型)
含水量	46 - 50 % (H+ 型)
平均直径	650 ± 50 µm
均一系数（最大）	1.2
转型率 (最低)	99.9 % (H+ 型)
杂质 铁（最大）	50 ppm
杂质 钠（最大）	40 ppm
杂质 重金属（最大）	40 ppm
比重	1.22
包装密度（大约）	760 - 800 g/L (47.5 - 50.0 lb/ft³)
温度限制	120 °C (248.0 °F)

水力学特性

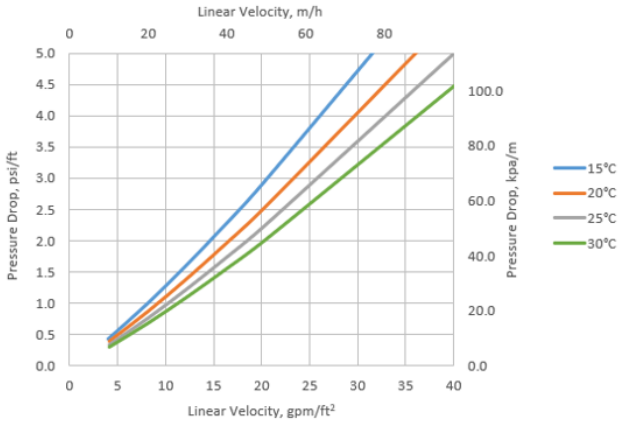
压降

离子交换树脂的压降取决于粒度分布、床层高度、树脂颗粒间空隙体积，以及物料的流速和粘度。任何对这些参数的影响-比如被树脂床层截住的颗粒物、对树脂床层的异常压缩、床层的不规则分布-都会对压降产生不利影响，造成压头损失。针对不同的物料质量、应用环境和系统设计，流速可能处于10 – 40 BV/h范围内变化。

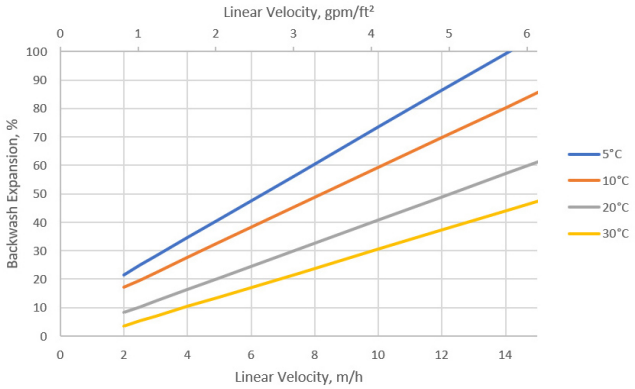
反洗

在自下而上反洗过程中，应控制反洗膨胀率在50%到70%之间，至少保持10到15分钟。该操作除去（运行过程中截留的物料中的）颗粒物，清除气泡，并重新规整树脂颗粒，确保最小的流动阻力。第一次投入前，大约30分钟的充分反洗，通常就足以对树脂床层进行适当的规整。 值得注意的是，相同流速下反洗膨胀率随温度降低而而升高。必须注意，应避免将树脂床层反洗膨胀过甚而导致树脂从顶部流失。

床层压降



树脂床反洗膨胀率



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